

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants :Isao SAKAMOTO et al.

Group Art Unit : 1726

Appl. No. : 10/598,124

Examiner : TAKEUCHI, YOSHITOSHI

Filed : August 18, 2006

Confirmation No. : 1323

For : SOLDER COMPOSITION AND METHOD OF BUMP FORMATION
THEREWITH

REQUEST TO RESTART PERIOD FOR RESPONSE

Commissioner for Patents
U.S. Patent and Trademark Office
Customer Service Window, Mail Stop
Randolph Building
401 Dulany Street
Alexandria, VA 22314

Sir :

Applicants note that the Non-Final Office Action dated February 16, 2012 is incomplete in omitting a complete copy of Lee, "Reflow Soldering Processes and Troubleshooting SMT, BGA, CSP and Flip Chip Technologies" as noted on the Form PTO-892. Applicants found that pages 41, 42, 47, and 49 – 51 were not included in the provided copy. The document is utilized in a rejection under 35 U.S.C. 103(a), set forth on pages 5 through 20 of the Office Action.

Therefore, Applicants respectfully request the forwarding of a complete copy of Lee, "Reflow Soldering Processes and Troubleshooting SMT, BGA, CSP and Flip Chip Technologies" including all pages relied upon in the rejection and the restarting of the period for response.

Authorization is hereby provided to charge any fee necessary for entry and/or consideration of this paper to Deposit Account No. 19-0089.

Should the Examiner have any questions regarding this application, she is invited to contact the undersigned at the below-listed telephone number.

Respectfully Submitted,
Isao SAKAMOTO et al.

/Sean Myers-Payne/
Reg. No. 42,920
Sean Myers-Payne

Bruce H. Bernstein
Reg. No. 29027

GREENBLUM & BERNSTEIN, P.L.C.
1950 Roland Clarke Place
Reston, VA 20191
(703) 716-1191